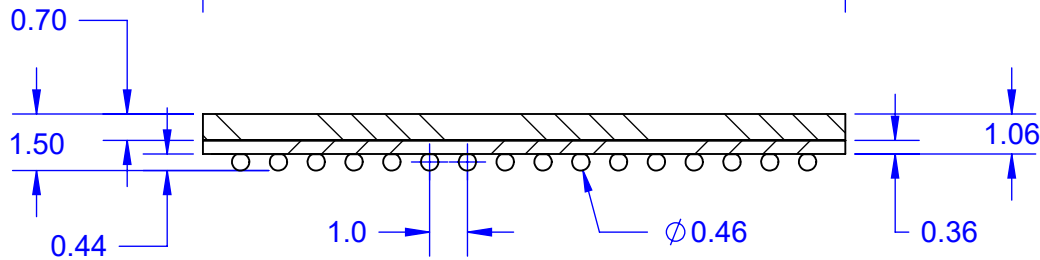
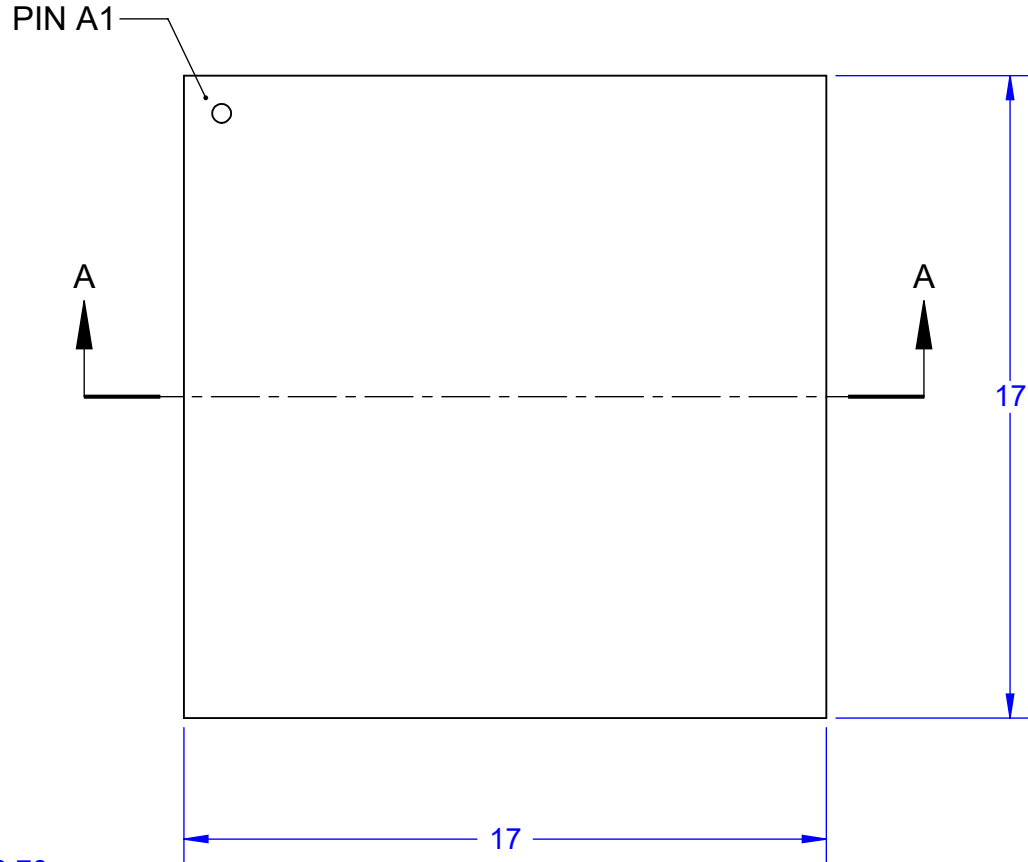


TOP VIEW

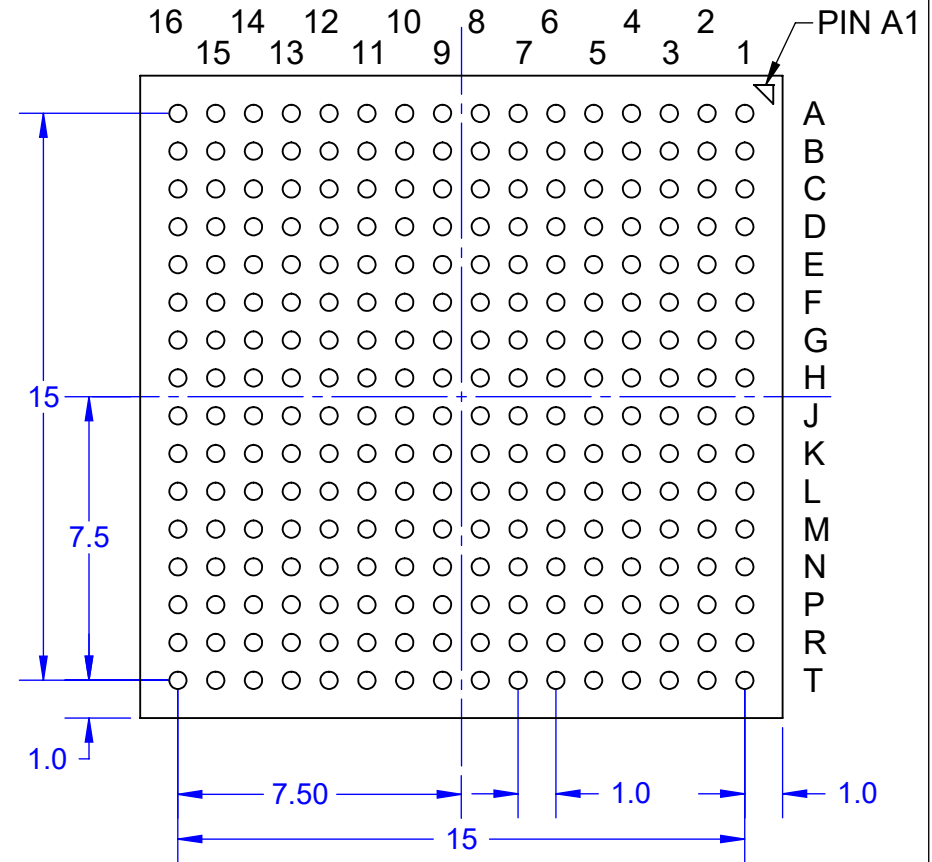


SECTION A-A

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA256T1.0C-ISO	Sn96.5/Ag3.0/Cu0.5	SAC35	YES	NO
BGA256T1.0-ISO	Sn63/Pb37	Sn63	NO	NO

BALL VIEW

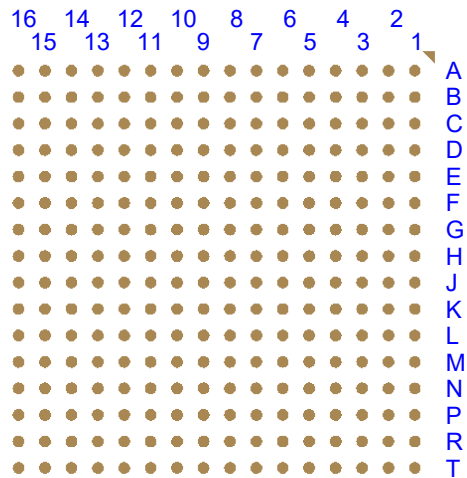


Notes: (Unless Otherwise Specified).

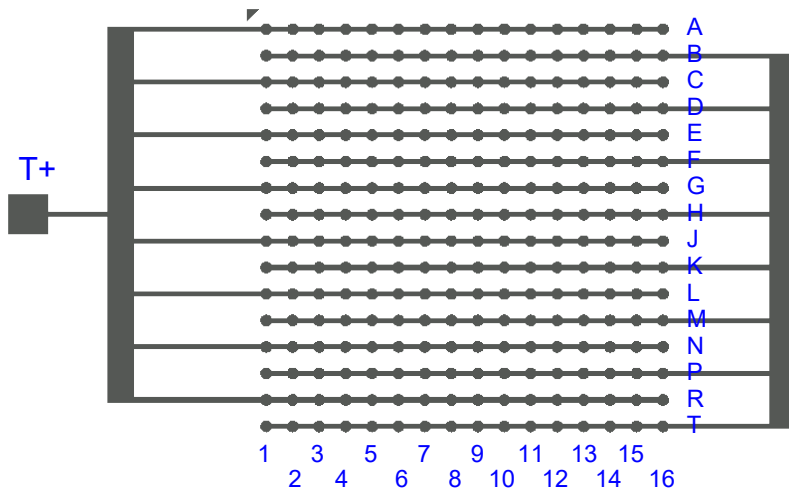
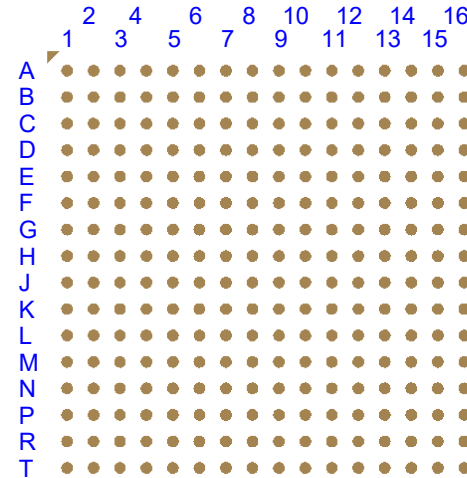
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.46mm (18 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.40mm (15.7 MIL).
- 5) PAD Cu DIAMETER: 0.46mm (18 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE: NONE.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

APPROVALS	DATE				
DRAWN T.Au	7/27/2025				
ENG M. Hart	7/27/2025	TITLE BGA256T1.0-ISO ISOLATED DUMMY			
MFG					
QA		SCALE 5:1	SIZE A	DRAWING NO. 511600	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			
					SHEET 1 OF 3

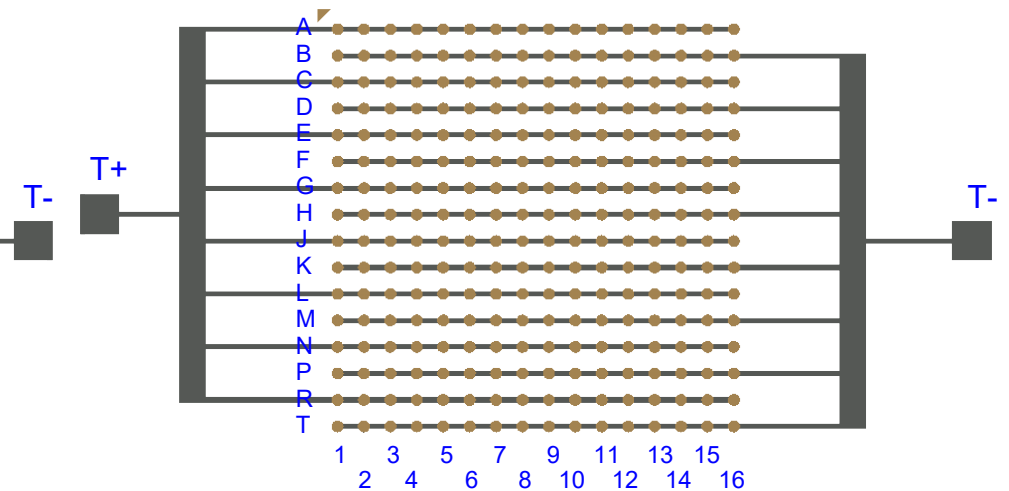
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



S.I.R TEST BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.381 (15 MIL).
- 3) PCB TRACING LINE WIDTH 0.20mm (8 MIL).
- 4) NSMD PAD OPENING 0.50mm (20 MIL).

TopLine®

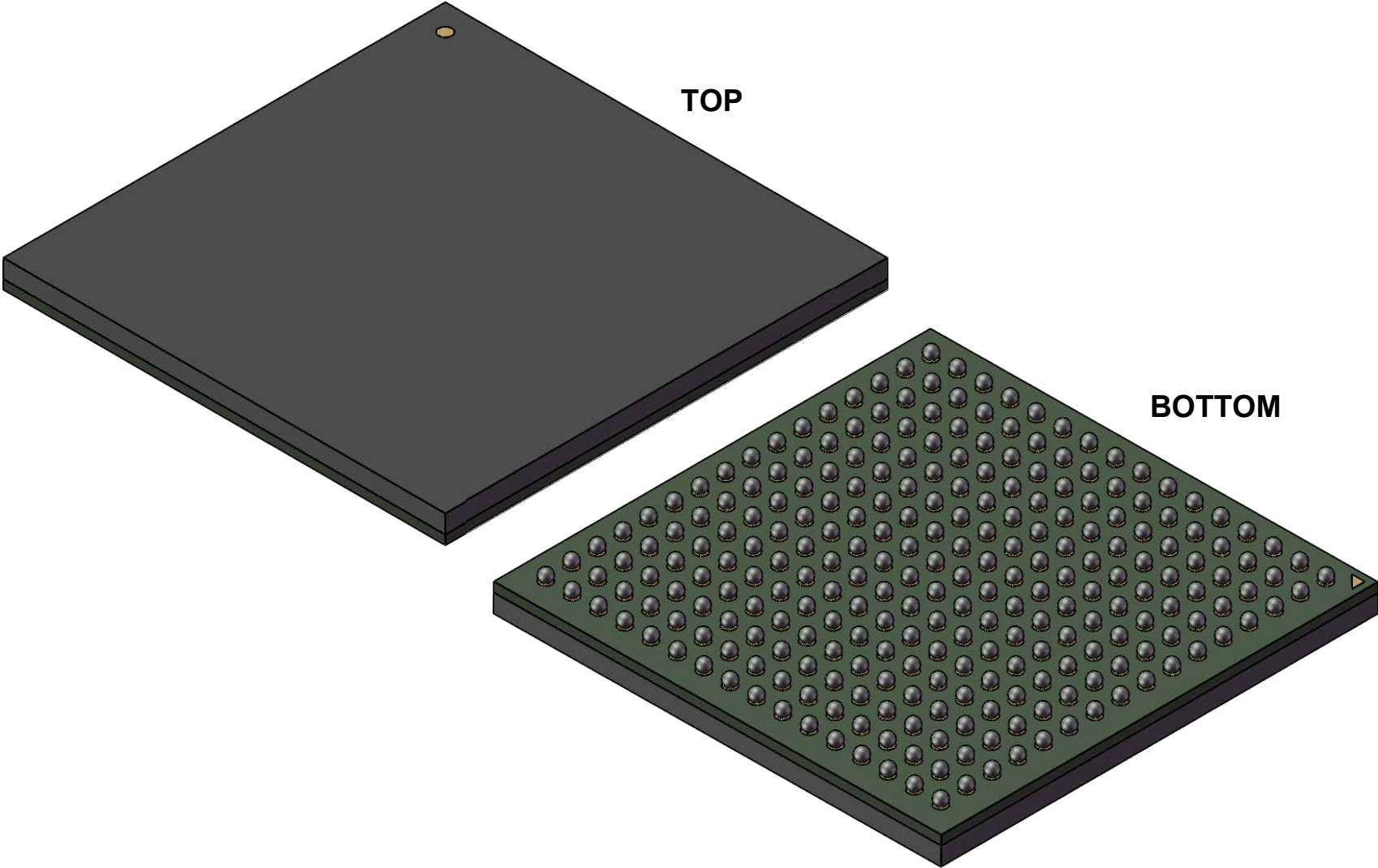
TITLE BGA256T1.0-ISO
ISOLATED DUMMY

SCALE 3.5:1	SIZE A	DRAWING NO. 511600	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 3

MODEL



TOP

BOTTOM

TopLine[®]			
TITLE		BGA256T1.0-ISO ISOLATED DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	511600	A
DO NOT SCALE DRAWING			SHEET 3 OF 3